



Material Content Data Sheet



Halogen-Free

Sales Product Name	BSC022N04LS6	Issued	13. April 2021
MA#	MA005209722		
Package	PG-TDSON-8-25	Weight*	113.68 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.663	0.58	0.58	5834	5834
leadframe	inorganic material	phosphorus	7723-14-0	0.016	0.01		137	
	non noble metal	iron	7439-89-6	0.052	0.05		456	
	non noble metal	copper	7440-50-8	51.740	45.52	45.58	455145	455738
wire	noble metal	gold	7440-57-5	0.047	0.04	0.04	413	413
encapsulation	organic material	carbon black	1333-86-4	0.083	0.07		730	
	plastics	epoxy resin	-	6.559	5.77		57699	
	inorganic material	silicondioxide	60676-86-0	34.871	30.68	36.52	306752	365181
leadfinish	non noble metal	tin	7440-31-5	1.392	1.22	1.22	12241	12241
plating	noble metal	silver	7440-22-4	0.194	0.17	0.17	1705	1705
solder	non noble metal	tin	7440-31-5	0.018	0.02		160	
	noble metal	silver	7440-22-4	0.023	0.02		200	
	non noble metal	lead	7439-92-1	0.868	0.76	0.80	7632	7992
heat sink CLIP	inorganic material	phosphorus	7723-14-0	0.005			45	
	non noble metal	iron	7439-89-6	0.017	0.02		151	
	non noble metal	copper	7440-50-8	17.131	15.07	15.09	150700	150896
*deviation	< 10%	Sum in total:				100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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